



# DB3-3500

## Diode

KKDB3-3500, November 2004 version

### ELECTRICAL PARAMETERS

#### Voltage ratings

Voltage class	$U_{RRM}$	$U_{RSM}$	$I_{RRM}$
	V	V	mA
30	3000	3100	100
32	3200	3300	
34	3400	3500	
36	3600	3700	
38	3800	3900	
40	4000	4100	

#### Electrical properties

Parameter	Unit	Test conditions	Value
Average forward current @ case temperature	$I_{F(AV)}$	A	3500
	$T_C$	°C	85
RMS forward current	$I_{F(RMS)}$	A	5500
Surge current	$I_{FSM}$	A	$T_j=150^\circ\text{C}$ , $U_R=0,8U_{RRM}$ , $t_p=10\text{ms}$
$I^2t$ – value	$I^2t$	$\text{kA}^2\text{s}$	10580
Forward voltage drop max.	$U_{FM}$	V	$T_j=25^\circ\text{C}$ , $I_{FM}=4000\text{A}$
Threshold voltage	$U_{F(T0)}$	V	0,64
Slope resistance	$r_F$	$\text{m}\Omega$	0,096
Reverse recovery time	$t_{rr}$	$\mu\text{s}$	$T_j=25^\circ\text{C}$ , $I_{FM}=2000\text{A}$ , $di_R/dt=25\text{A}/\mu\text{s}$

#### Thermal properties

Parameter	Unit	Test conditions	Value
Thermal resistance, junction to case	$R_{thJC}$	°C/W	two sided, DC
Thermal resistance, case to heatsink	$R_{thCS}$	°C/W	two sided
Operating junction temperature	$T_{jmin} \dots T_{jmax}$	°C	-40...+150
Storage temperature	$T_{stg}$	°C	-40...+150

#### Mechanical properties

Parameter	Unit	Value
Clamping force	$F_M$	kN
Weight	m	g

# DB3-3500

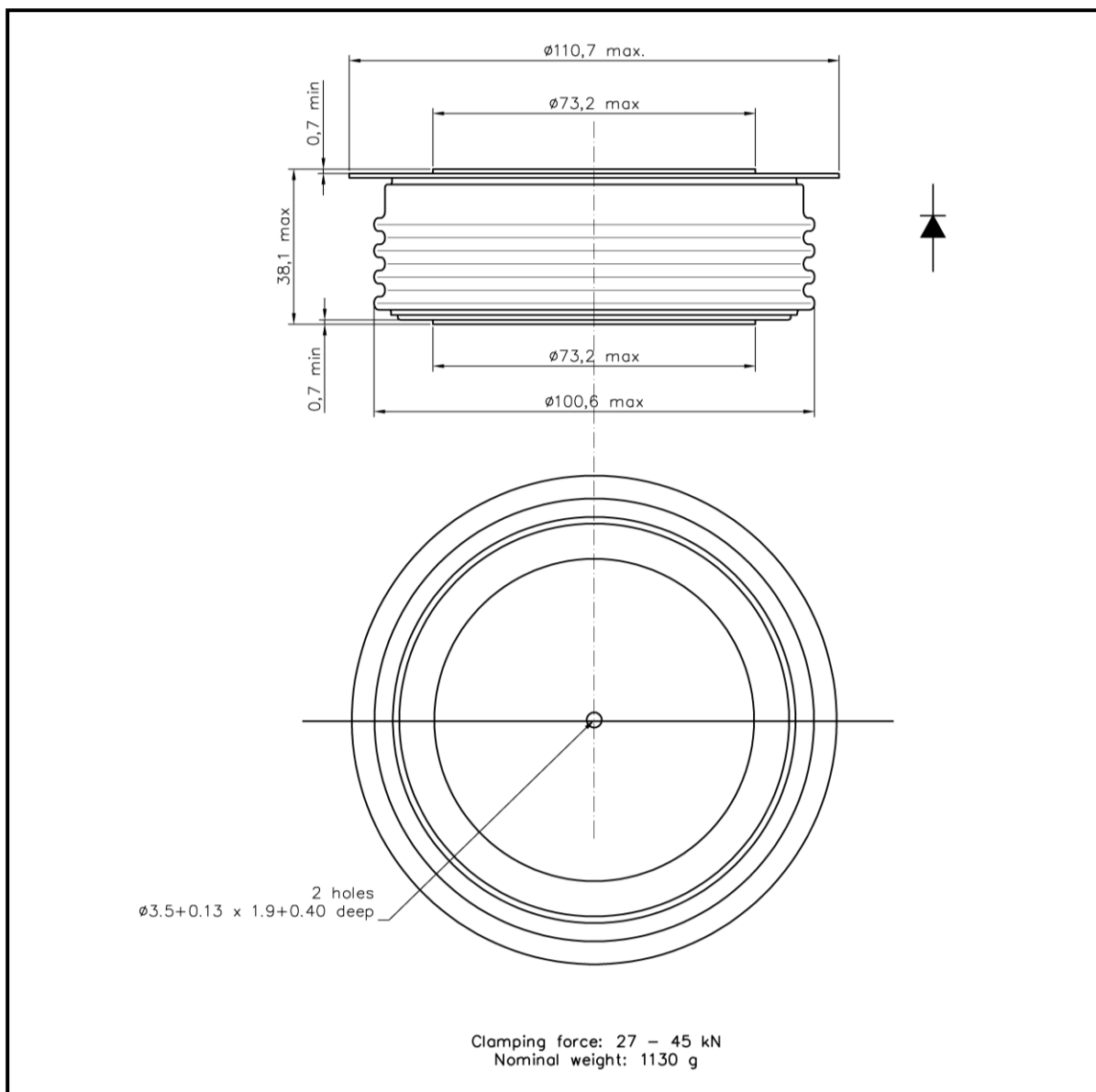
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Zakłady Elektroniczne  
**LAMINA S.A.**

KKDB3-3500, November 2004 version

### Package details



For further package information, please contact Sales & Marketing Department. All dimensions in mm, unless stated otherwise.  
Do not scale.

Zakłady Elektroniczne LAMINA S.A.  
Puławska 34  
PL-05-500 Piaseczno  
POLAND

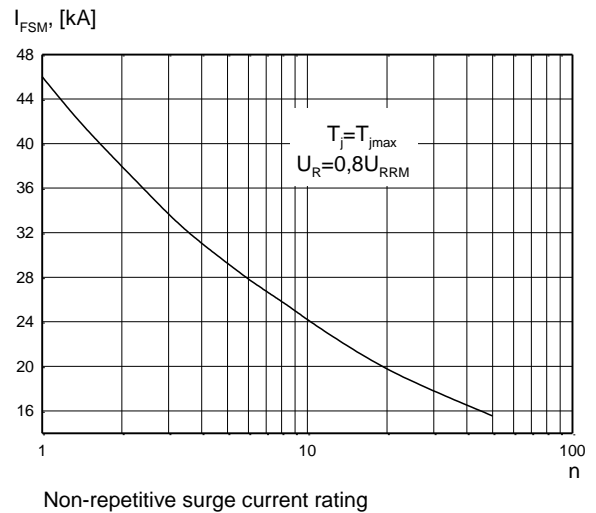
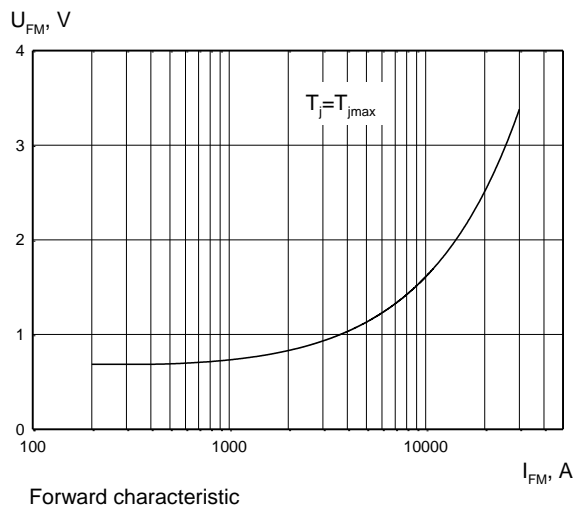
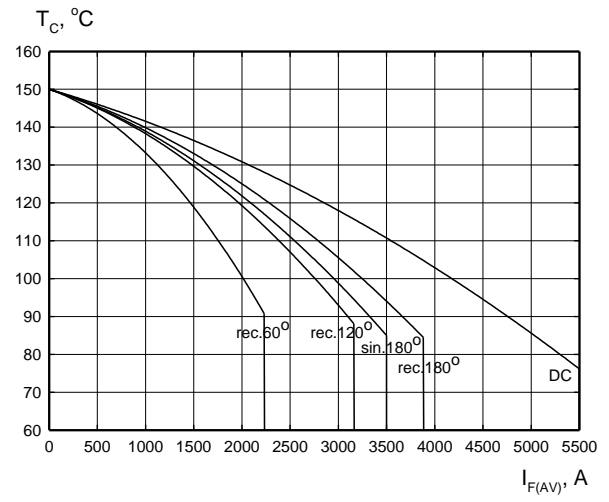
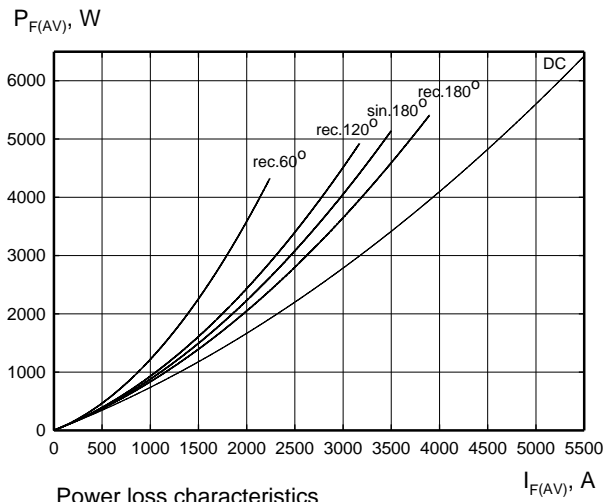
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### CHARACTERISTICS

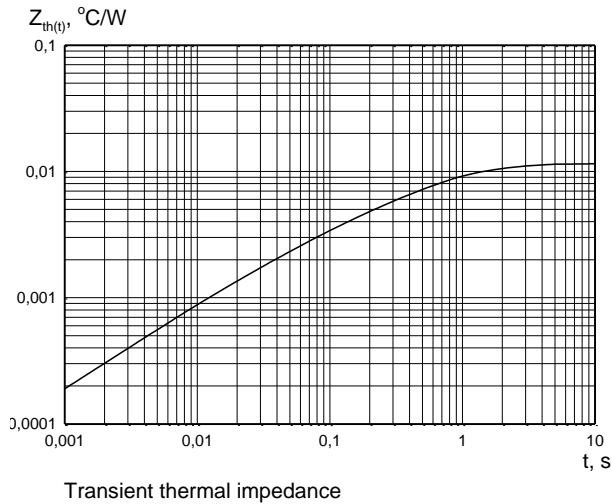


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## HEATSINKS

LAMINA S.I. has its own proprietary range of extruded aluminium heatsinks designed to optimise the performance of our semiconductors with natural and forced air flow. High efficiency water cooled copper heatsinks are also available.

## DEVICE CLAMPS

Disc devices require the correct clamping force to ensure their best operation. LAMINA S.I. offers a wide selection of clamps to suit all of our manufactured devices.

## POWER ASSEMBLY CAPABILITY

LAMINA S.I. provides a support for those customers requiring more than a basic semiconductor and offers precisely assembled Power Blocks according to factory or customer standards.

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

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